

PIN DESCRIPTION

SYMBOL	FUNCTION	DESCRIPTION
VCC	POWER	+5V $\pm 5\%$
429DI1 (A)	INPUT	ARINC receiver 1 positive input
429DI1 (B)	INPUT	ARINC receiver 1 negative input
429DI2 (A)	INPUT	ARINC receiver 2 positive input
429DI2 (B)	INPUT	ARINC receiver 2 negative input
$\overline{D/R1}$	OUTPUT	Receiver 1 data ready flag
$\overline{D/R2}$	OUTPUT	Receiver 2 data ready flag
SEL	INPUT	Receiver data byte selection (0 = BYTE 1) (1 = BYTE 2)
$\overline{EN1}$	INPUT	Data Bus control, enables receiver 1 data to outputs
$\overline{EN2}$	INPUT	Data Bus control, enables receiver 2 data to outputs if $\overline{EN1}$ is high
BD15	I/O	Data Bus
BD14	I/O	Data Bus
BD13	I/O	Data Bus
BD12	I/O	Data Bus
BD11	I/O	Data Bus
BD10	I/O	Data Bus
BD09	I/O	Data Bus
BD08	I/O	Data Bus
BD07	I/O	Data Bus
BD06	I/O	Data Bus
GND	POWER	0 V
BD05	I/O	Data Bus
BD04	I/O	Data Bus
BD03	I/O	Data Bus
BD02	I/O	Data Bus
BD01	I/O	Data Bus
BD00	I/O	Data Bus
$\overline{PL1}$	INPUT	Latch enable for byte 1 entered from data bus to transmitter FIFO.
$\overline{PL2}$	INPUT	Latch enable for byte 2 entered from data bus to transmitter FIFO. Must follow $\overline{PL1}$.
TX/R	OUTPUT	Transmitter ready flag. Goes low when ARINC word loaded into FIFO. Goes high after transmission and FIFO empty.
429DO	OUTPUT	"ONES" data output from transmitter.
$\overline{429DO}$	OUTPUT	"ZEROES" data output from transmitter.
ENTX	INPUT	Enable Transmission
\overline{CWSTR}	INPUT	Clock for control word register
CLK	INPUT	Master Clock input
TX CLK	OUTPUT	Transmitter Clock equal to Master Clock (CLK), divided by either 10 or 80.
\overline{MR}	INPUT	Master Reset, active low

FUNCTIONAL DESCRIPTION

CONTROL WORD REGISTER

The HI-8282 contains 10 data flip flops whose D inputs are connected to the data bus and clocks connected to CWSTR. Each flip flop provides options to the user as follows:

DATA BUS PIN	FUNCTION	CONTROL	DESCRIPTION
BDO5	SELF TEST	0 = ENABLE	If enabled, an internal connection is made passing 429DO and 429D0 to the receiver logic inputs
BDO6	RECEIVER 1 DECODER	1 = ENABLE	If enabled, ARINC bits 9 and, 10 must match the next two control word bits
BDO7	-	-	If Receiver 1 Decoder is enabled, the ARINC bit 9 must match this bit
BDO8	-	-	If Receiver 1 Decoder is enabled, the ARINC bit 10 must match this bit
BDO9	RECEIVER 2 DECODER	1 = ENABLE	If enabled, ARINC bits 9 and 10 must match the next two control word bits
BD10	-	-	If Receiver 2 Decoder is enabled, then ARINC bit 9 must match this bit
BD11	-	-	If Receiver 2 Decoder is enabled, then ARINC bit 10 must match this bit
BD12	INVERT XMTR PARITY	1 = ENABLE	Logic 0 enables normal odd parity and Logic 1 enables even parity output in transmitter 32nd bit
BD13	XMTR DATA CLK SELECT	0 = ÷10 1 = ÷80	CLK is divided either by 10 or 80 to obtain XMTR data clock
BD14	RCVR DTA CLK SELECT	0 = ÷10 1 = ÷80	CLK is divided either by 10 or 80 to obtain RCVR data clock

ARINC 429 DATA FORMAT

The following table shows the bit positions in exchanging data with the receiver or the transmitter. ARINC bit 1 is the first bit transmitted or received.

BYTE 1															
DATA BUS	BD 15	BD 14	BD 13	BD 12	BD 11	BD 10	BD 09	BD 08	BD 07	BD 06	BD 05	BD 04	BD 03	BD 02	BD 01
ARINC BIT	13	12	11	10	9	31	30	32	1	2	3	4	5	6	7

BYTE 2															
DATA BUS	BD 15	BD 14	BD 13	BD 12	BD 11	BD 10	BD 09	BD 08	BD 07	BD 06	BD 05	BD 04	BD 03	BD 02	BD 01
ARINC BIT	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15

THE RECEIVERS

ARINC BUS INTERFACE

Figure 1 shows the input circuit for each receiver. The ARINC 429 specification requires the following detection levels:

STATE	DIFFERENTIAL VOLTAGE
ONE	+6.5 Volts to +13 Volts
NULL	+2.5 Volts to -2.5 Volts
ZERO	-6.5 Volts to -13 Volts

The HI-8282 guarantees recognition of these levels with a common mode voltage with respect to GND less than ±4V for the worst case condition (4.75V supply and 13v signal level).

Design tolerances guarantee detection of the above levels, so the actual acceptance ranges are slightly larger. If the ARINC signal is out of the actual acceptance ranges, including the nulls, the chip rejects the data.

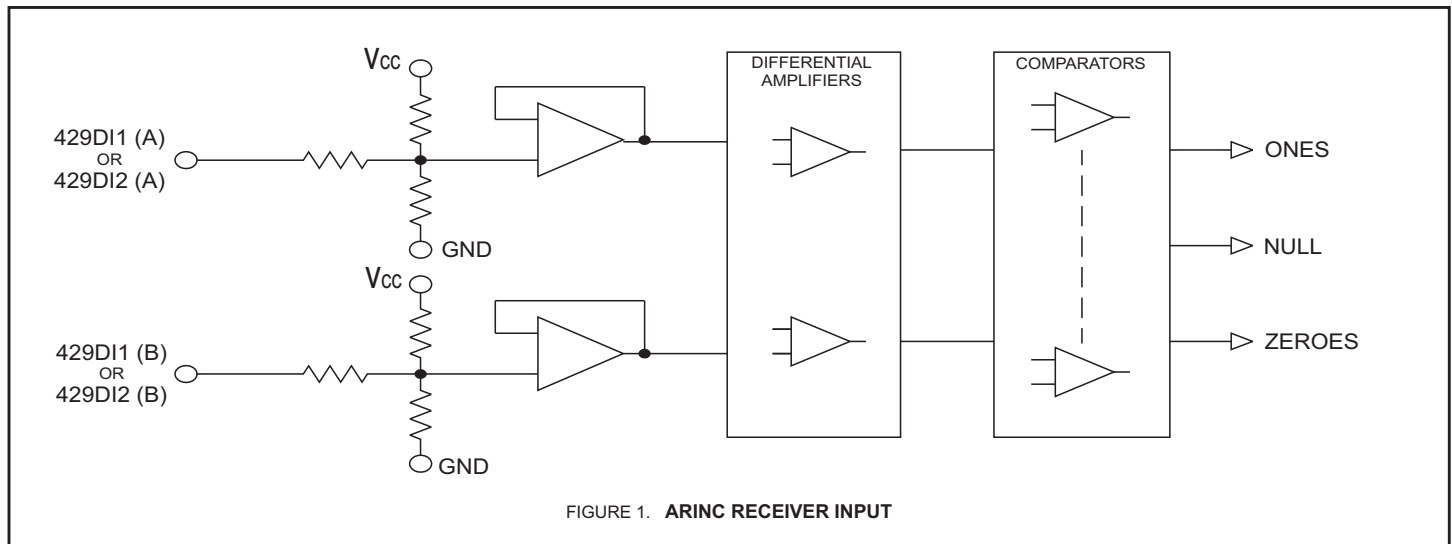


FIGURE 1. ARINC RECEIVER INPUT

FUNCTIONAL DESCRIPTION (cont.)

RECEIVER LOGIC OPERATION

Figure 2 is a block diagram showing each receiver's logic.

BIT TIMING

ARINC 429 specifies the following timing for received data:

	<u>HIGH SPEED</u>	<u>LOW SPEED</u>
BIT RATE	100K BPS \pm 1%	12K -14.5K BPS
PULSE RISE TIME	1.5 \pm 0.5 μ sec	10 \pm 5 μ sec
PULSE FALL TIME	1.5 \pm 0.5 μ sec	10 \pm 5 μ sec
PULSE WIDTH	5 μ sec \pm 5%	34.5 - 41.7 μ sec

The HI-8282 accepts signals meeting these specifications and rejects signals outside these tolerances using the method described here:

1. The timing logic requires an accurate 1.0 MHz clock source. Less than 0.1% error is recommended.
2. The sampling shift registers are 10 bits long and must show three consecutive Ones, Zeros or Nulls to be considered valid data. To qualify data bits, One or Zero in the upper bits of the sampling shift register must be followed by Null in the lower bits within the data bit time. A word gap Null requires three consecutive Nulls in both the upper and lower bits of the sampling shift register. This guarantees the minimum pulse width.
3. Each data bit must follow its predecessor by not less than 8 samples and not more than 12 samples. In this manner the bit rate is checked. With exactly 1 MHz input clock frequency, the acceptable data bit rates are as follows:

	<u>HIGH SPEED</u>	<u>LOW SPEED</u>
DATA BIT RATE MIN	83K BPS	10.4K BPS
DATA BIT RATE MAX	125K BPS	15.6K BPS

4. The Word Gap timer samples the Null shift register every 10 input clocks (80 for low speed) after the last data bit of a valid reception. If the Null is present, the Word Gap counter is incremented. A count of 3 enables the next reception.

RECEIVER PARITY

The 32nd bit of received ARINC words stored in the receive FIFO is used as a Parity Flag indicating whether good Odd parity is received from the incoming ARINC word.

Odd Parity Received

The parity bit is reset to indicate correct parity was received and the resulting word is then written to the receive FIFO.

Even Parity Received

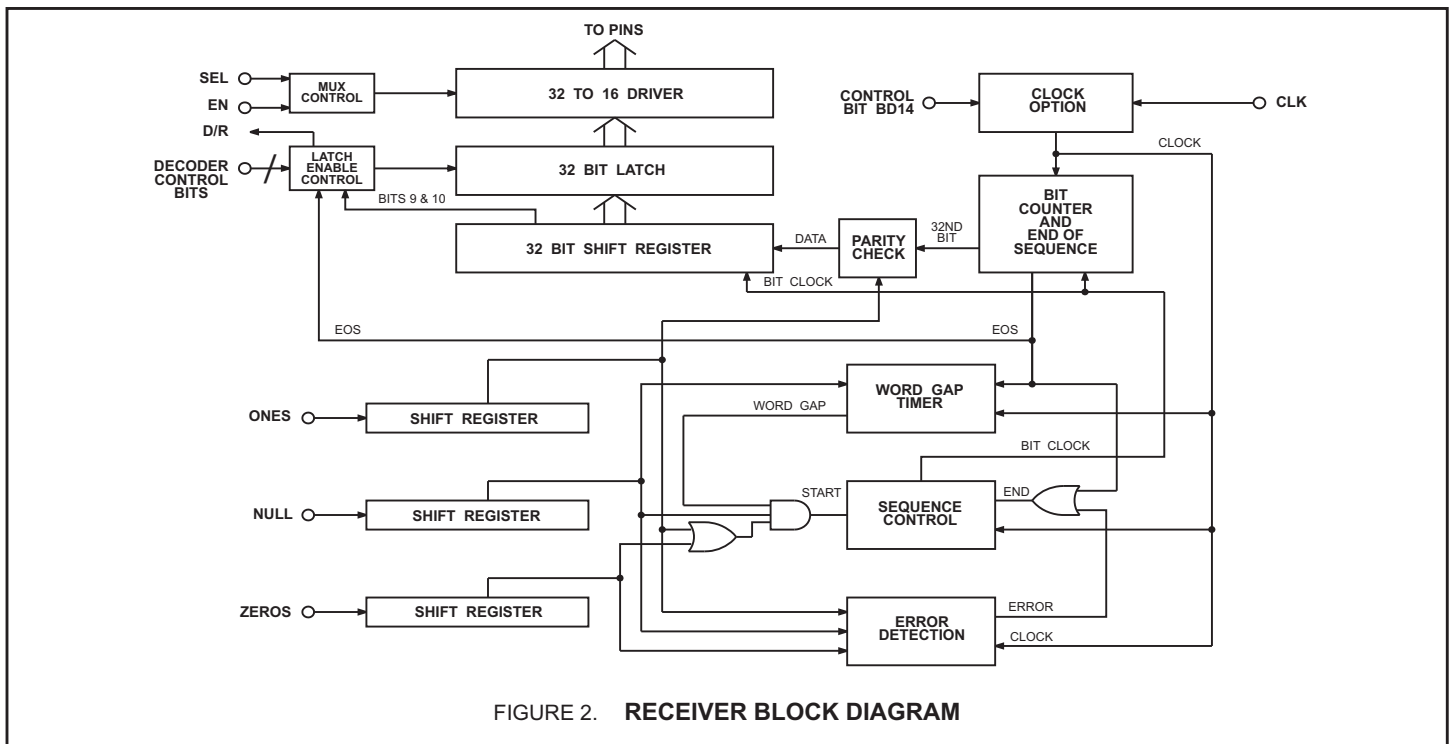
The receiver sets the 32nd bit to a "1", indicating a parity error and the resulting word is then written to the receive FIFO.

Therefore, the 32nd bit retrieved from the receiver FIFO will always be a "0" when valid (odd parity) ARINC 429 words are received.

RETRIEVING DATA

Once 32 valid bits are recognized, the receiver logic generates an End of Sequence (EOS). If the receiver decoder is enabled and the 9th and 10th ARINC bits match the control word program bits or if the receiver decoder is disabled, then EOS clocks the data ready flag flip flop to a "1", D/R1 or D/R2 (or both) will go low. The data flag for a receiver remains low until after both ARINC bytes from that receiver are retrieved. This is accomplished by first activating EN with SEL, the byte selector, low to retrieve the first byte and then activating EN with SEL high to retrieve the second byte. EN1 retrieves data from receiver 1 and EN2 retrieves data from receiver 2.

If another ARINC word is received and a new EOS occurs before the two bytes are retrieved, the data is overwritten by the new word.



FUNCTIONAL DESCRIPTION (cont.)

TRANSMITTER

A block diagram of the transmitter section is shown in Figure 3.

FIFO OPERATION

The FIFO is loaded sequentially by first pulsing $\overline{PL1}$ to load byte 1 and then $\overline{PL2}$ to load byte 2. The control logic automatically loads the 31 bit word in the next available position of the FIFO. If TX/R, the transmitter ready flag, is high (FIFO empty), then 8 words, each 31 bits long, may be loaded. If TX/R is low, then only the available positions may be loaded. If all 8 positions are full, the FIFO ignores further attempts to load data.

DATA TRANSMISSION

When ENTX goes high, enabling transmission, the FIFO positions are incremented with the top register loading into the data transmission shift register. Within 2.5 data clocks the first data bit appears at either 429DO or 429D0. The 31 bits in the data transmission shift register are presented sequentially to the outputs in the ARINC 429 format with the following timing:

	HIGH SPEED	LOW SPEED
ARINC DATA BIT TIME	10 Clocks	80 Clocks
DATA BIT TIME	5 Clocks	40 Clocks
NULL BIT TIME	5 Clocks	40 Clocks
WORD GAP TIME	40 Clocks	320 Clocks

The word counter detects when all loaded positions are transmitted and sets the transmitter ready flag, TX/R, high.

TRANSMITTER PARITY

The parity generator counts the ONES in the 31-bit word. If the BD12 control word bit is set low, the 32nd bit transmitted will make parity odd. If the control bit is high, the parity is even.

SELF TEST

If the BD05 control word bit is set low, the digital outputs of the transmitter are internally connected to the logic inputs of the receivers, bypassing the analog bus interface circuitry. Data to Receiver 1 is as transmitted and data to Receiver 2 is the complement. All data transmitted during self test is also present on the TXA(OUT) and TXB(OUT) line driver outputs.

SYSTEM OPERATION

The two receivers are independent of the transmitter. Therefore, control of data exchanges is strictly at the option of the user. The only restrictions are:

1. The received data may be overwritten if not retrieved within one ARINC word cycle.
2. The FIFO can store 8 words maximum and ignores attempts to load addition data if full.
3. Byte 1 of the transmitter data must be loaded first.
4. Either byte of the received data may be retrieved first. Both bytes must be retrieved to clear the data ready flag.
5. After ENTX, transmission enable, goes high it cannot go low until TX/R, transmitter ready flag, goes high. Otherwise, one ARINC word is lost during transmission.

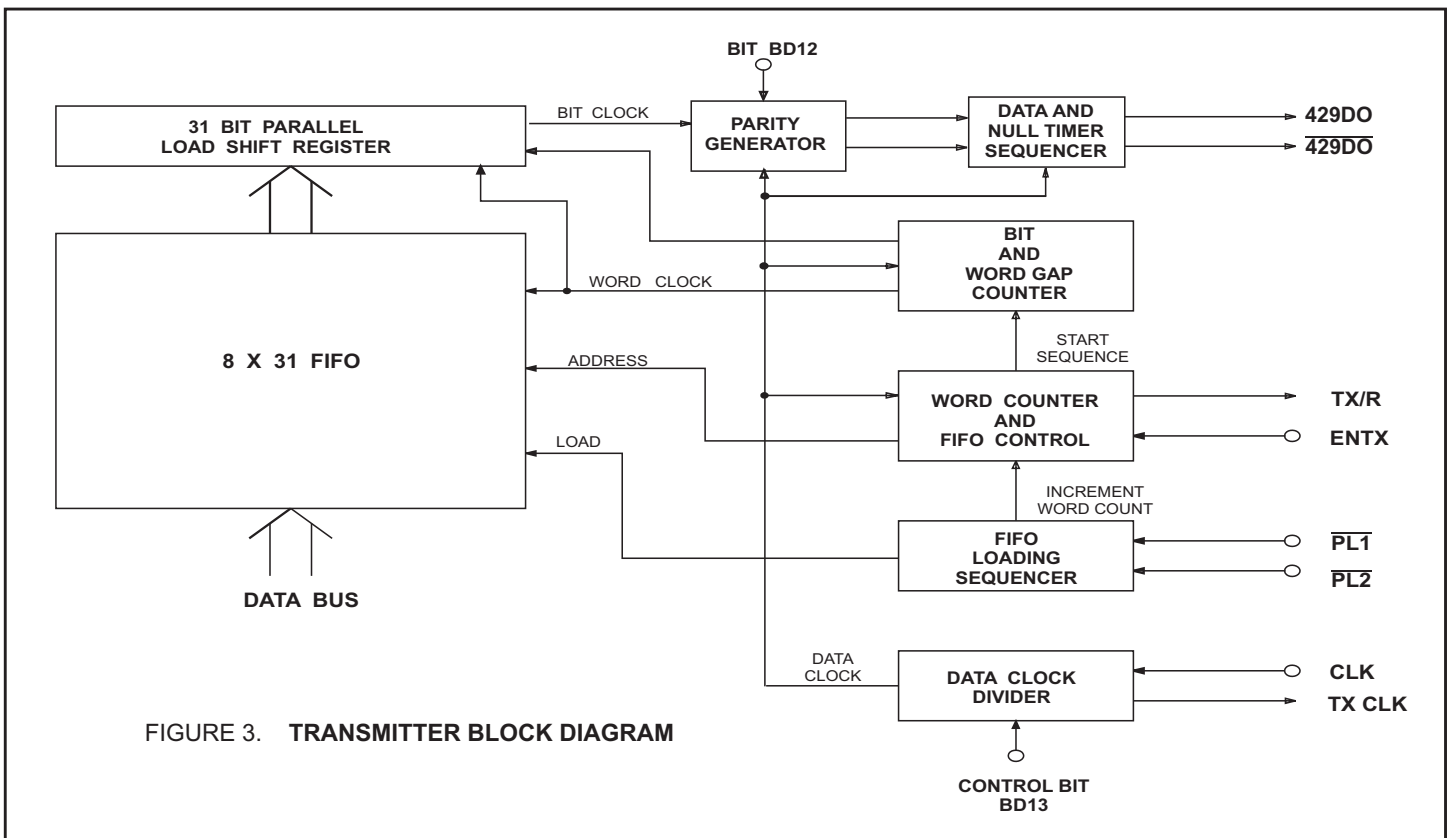


FIGURE 3. TRANSMITTER BLOCK DIAGRAM

FUNCTIONAL DESCRIPTION (cont.)

REPEATER OPERATION

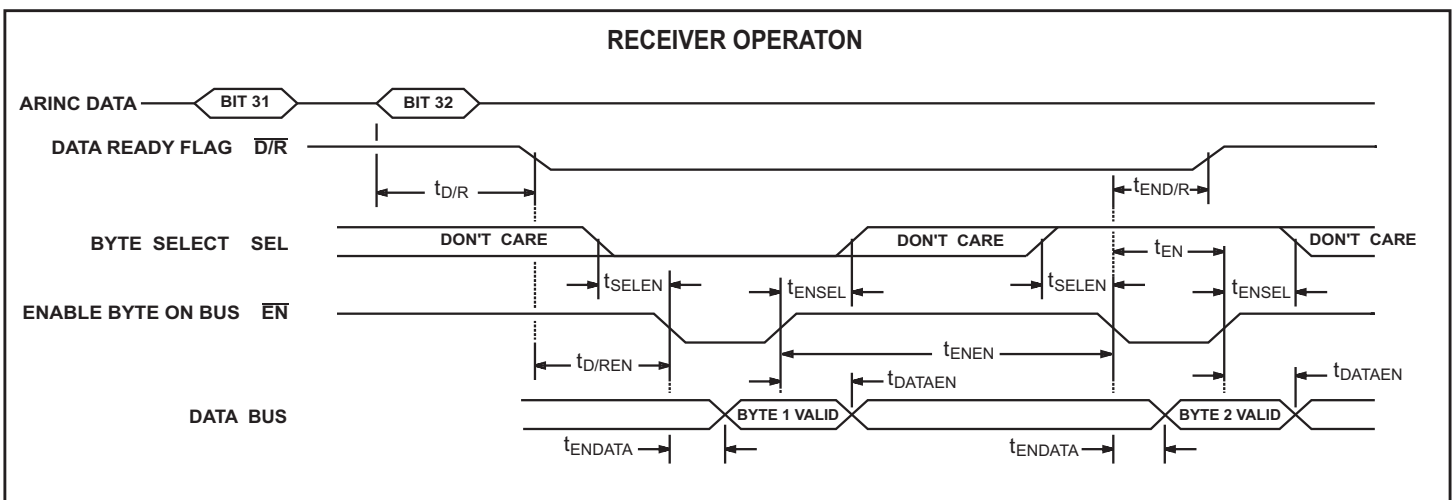
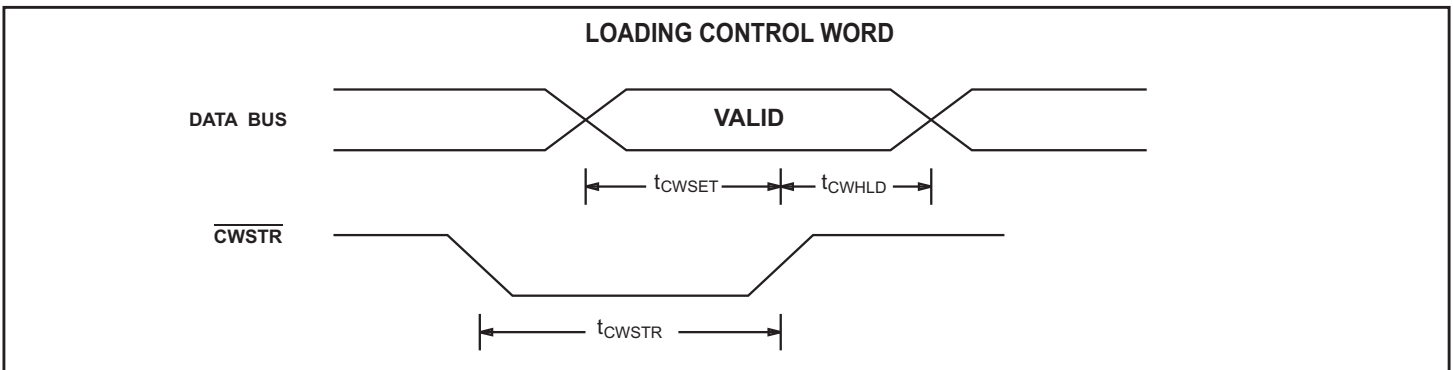
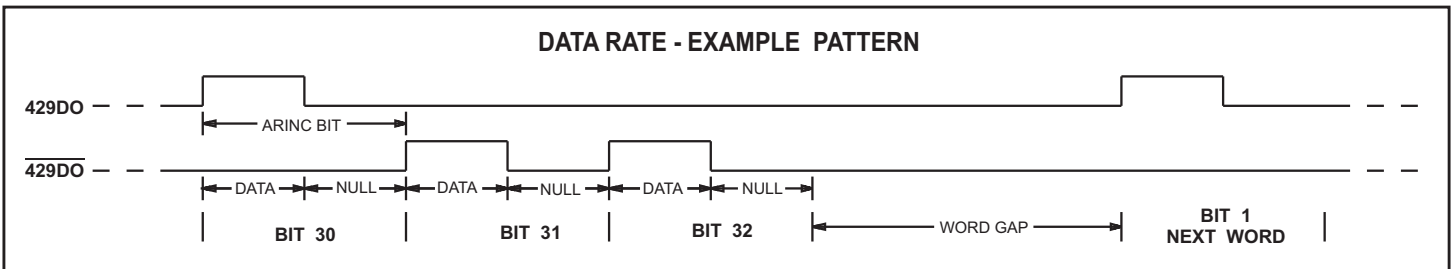
Repeater mode of operation allows a data word received by the HI-8282 to be placed directly into the Transmit FIFO for transmission. After a 32-bit word has been shifted into the receiver shift register, the $\overline{D/R}$ flag goes low. A logic "0" is placed on the SEL line and \overline{EN} is strobed. This is the same procedure as for normal receiver operation, placing the lower byte (16) of the data word on the data bus. By strobing $\overline{PL1}$ at the same time as \overline{EN} , the byte is also transferred into the Transmit FIFO. SEL is then taken high and \overline{EN} is strobed again to place the upper data word byte onto the data bus. By strobing $\overline{PL2}$ at the same time as \overline{EN} , the second data word byte is also transferred to the Transmit FIFO. The data word is now ready for transmission, according to the parity programmed into the Control Word register.

In normal (non-repeater) operation, either byte of the received data word may be read first by using the SEL input. During repeater operation however, data word lower byte must always be read first. While the data is being read, it is loading concurrently into the Transmit FIFO, which always loads lower byte first.

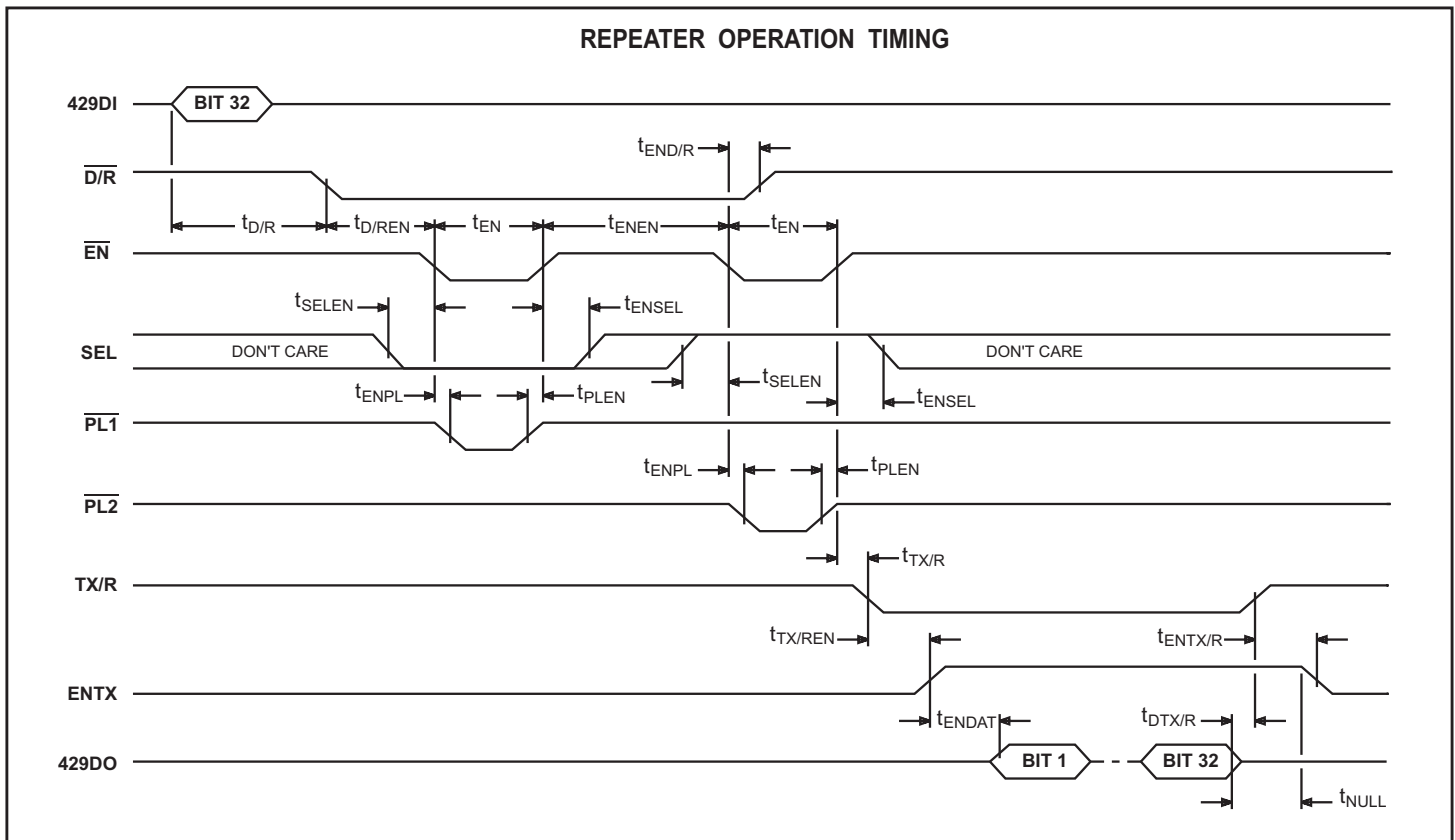
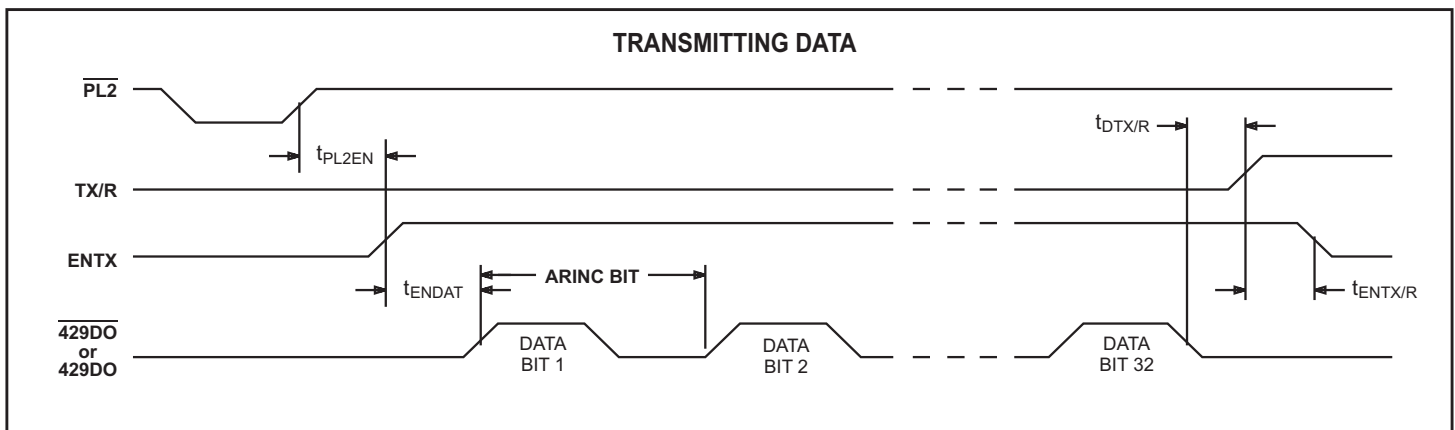
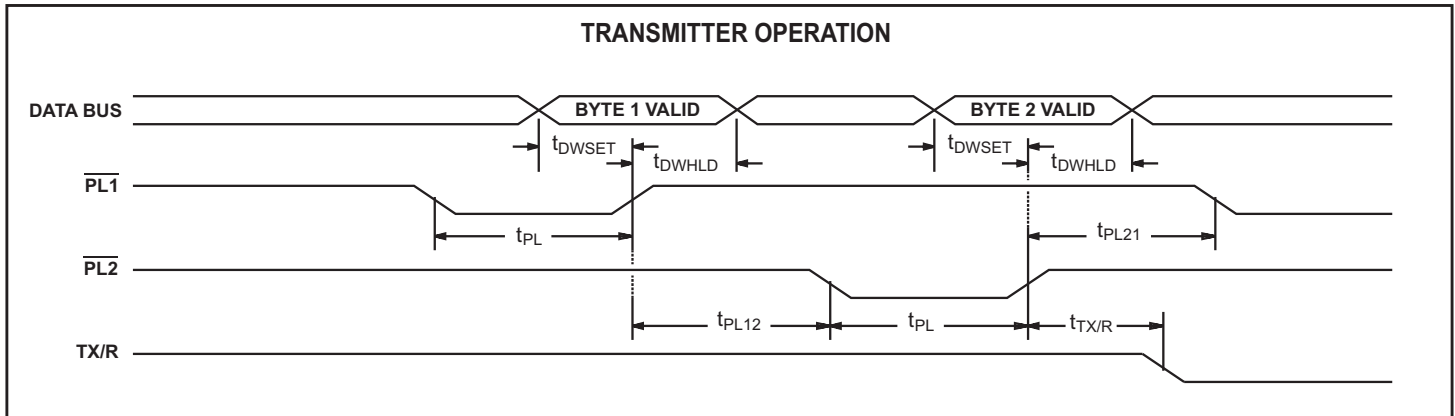
MASTER RESET (\overline{MR})

Upon Master Reset, data transmission and reception are immediately terminated, all three FIFOs are cleared as are the FIFO flags at the device pins and in the Status Register. The Control Word register is not affected by a Master Reset.

TIMING DIAGRAMS



TIMING DIAGRAMS (cont.)



ABSOLUTE MAXIMUM RATINGS

Supply Voltage V_{CC}	-0.3V to +7V	Power Dissipation	500mW
Voltage at ARINC input pins	-120V to +120V	Operating Temperature Range: (Industrial)	-40°C to +85°C
Voltage at any other pin	-0.3V to $V_{CC}+0.3V$	(Extended)	-55°C to +125°C
DC Current Drain per input pin	10mA	Storage Temperature Range:	-65°C to +150°C

NOTE: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only. Functional operation of the device at these or any other conditions above those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

DC ELECTRICAL CHARACTERISTICS

$V_{CC} = 5V \pm 5\%$, $GND = 0V$, T_A = Operating Temperature Range (unless otherwise specified).

PARAMETER	SYMBOL	CONDITIONS	LIMITS			UNIT	
			MIN	TYP	MAX		
ARINC INPUTS							
Differential Input Voltage:	ONE ZERO NULL	V_{IH} V_{IL} V_{NUL}	Pins 2 to 3, 4 to 5: Common mode voltage less than $\pm 4V$ with respect to GND	6.5 -13.0 -2.5	10.0 -10.0 0	13.0 -6.5 2.5	V V V
Input Resistance:	Differential To GND To Vcc	R_I R_G R_H		12 12 12	27 27		K Ω K Ω k Ω
Input Current:	Input Sink Input Source	I_{IH} I_{IL}		-450		200	μA μA
Input Capacitance: (Guaranteed but not tested)	Differential To GND To Vcc	C_I C_G C_H	Pins 2 to 3, 4 to 5			20 20 20	pF pF pF
BI-DIRECTIONAL INPUTS							
Input Voltage:	Input Voltage HI Input Voltage LO	V_{IH} V_{IL}		2.1		0.7	V V
Input Current:	Input Sink Input Source	I_{IH} I_{IL}		-1.5		1.5	μA μA
ALL OTHER INPUTS							
Input Voltage:	Input Voltage HI Input Voltage LO	V_{IH} V_{IL}		3.5		0.7	V V
Input Current:	Input Sink Input Source	I_{IH} I_{IL}		-20		10	μA μA
OUTPUTS							
Output Voltage:	Logic "1" Output Voltage Logic "0" Output Voltage	V_{OH} V_{OL}	$I_{OH} = -1.5mA$ $I_{OL} = 1.8mA$	2.7		0.4	V V
Output Current: (Bi-directional Pins)	Output Sink Output Source	I_{OL} I_{OH}	$V_{OUT} = 0.4V$ $V_{OUT} = V_{CC} - 0.4V$	3.0 1.5			mA mA
Output Current: (All Other Outputs)	Output Sink Output Source	I_{OL} I_{OH}	$V_{OUT} = 0.4V$ $V_{OUT} = V_{CC} - 0.4V$	3.6 1.5			mA mA
Output Capacitance:		C_O				15	pF
SUPPLY INPUT							
Standby Supply Current:		I_{CC1}				20	mA
Operating Supply Current:		I_{CC2}				20	mA

AC ELECTRICAL CHARACTERISTICS

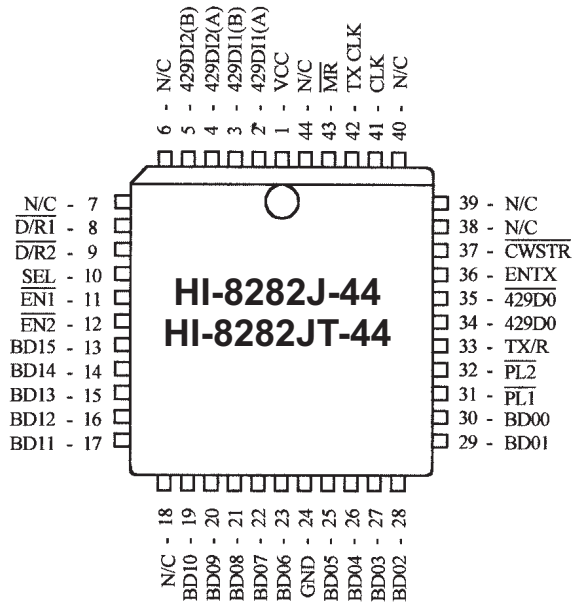
V_{cc} = 5V, GND = 0V, TA = Operating Temperature Range and f_{clk} = 1MHz \pm 0.1% with 60/40 duty cycle

PARAMETER	SYMBOL	LIMITS			UNITS
		MIN	TYP	MAX	
CONTROL WORD TIMING					
Pulse Width - \overline{CWSTR} Setup - DATA BUS Valid to \overline{CWSTR} HIGH Hold - \overline{CWSTR} HIGH to DATA BUS Hi-Z	tCWSTR tCWSET tCWHLd	130 140 0			ns ns ns
RECEIVER TIMING					
Delay - Start ARINC 32nd Bit to $\overline{D/R}$ LOW: High Speed Low Speed	tD/R tD/R			16 128	μ s μ s
Delay - $\overline{D/R}$ LOW to \overline{EN} LOW Delay - \overline{EN} LOW to $\overline{D/R}$ HIGH	tD/REN tEND/R	0		200	ns ns
Setup - SEL to \overline{EN} LOW Hold - SEL to \overline{EN} HIGH	tSELEN tENSEL	20 50			ns ns
Delay - \overline{EN} LOW to DATA BUS Valid Delay - \overline{EN} HIGH to DATA BUS Hi-Z	tENDATA tDATAEN			200 30	ns ns
Pulse Width - $\overline{EN1}$ or $\overline{EN2}$ Spacing - \overline{EN} HIGH to next \overline{EN} LOW	tEN tENEN	240 50			ns ns
FIFO TIMING					
Pulse Width - $\overline{PL1}$ or $\overline{PL2}$	tPL	200			ns
Setup - DATA BUS Valid to \overline{PL} HIGH Hold - \overline{PL} HIGH to DATA BUS Hi-Z	tDWSET tDWHLD	110 20			ns ns
Spacing - $\overline{PL1}$ to $\overline{PL2}$	tPL12	0			ns
Spacing - $\overline{PL2}$ to $\overline{PL1}$	tPL21	250			ns
Delay - $\overline{PL2}$ HIGH to TX/R LOW	tTX/R			840	ns
TRANSMISSION TIMING					
Spacing - $\overline{PL2}$ HIGH to ENTX HIGH	tPL2EN	0			μ s
Delay - ENTX HIGH to TXA(OUT) or TXB(OUT): High Speed Delay - ENTX HIGH to TXA(OUT) or TXB(OUT): Low Speed	tENDAT tENDAT			25 200	μ s μ s
Delay - 32nd ARINC Bit to TX/R HIGH	tDTX/R			400	ns
Spacing - TX/R HIGH to ENTX LOW	tENTX/R	0			ns
REPEATER OPERATION TIMING					
Delay - \overline{EN} LOW to \overline{PL} LOW	tENPL	0			ns
Hold - \overline{PL} HIGH to \overline{EN} HIGH	tPLEN	0			ns
Delay - TX/R LOW to ENTX HIGH	tTX/REN	0			ns
Master Reset Pulse Width	tMR	400			ns
ARINC Data Rate and Bit Timing				$\pm 1\%$	

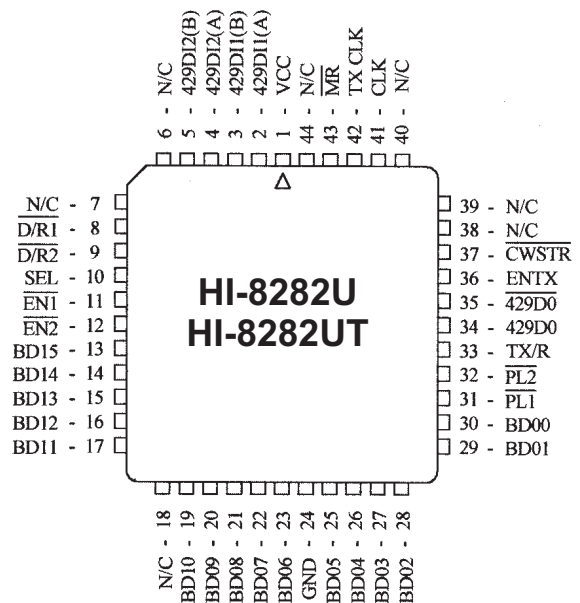
ADDITIONAL HI-8282 PIN CONFIGURATIONS

(See page 1 for the 40-pin Ceramic Side-Brazed DIP Package)

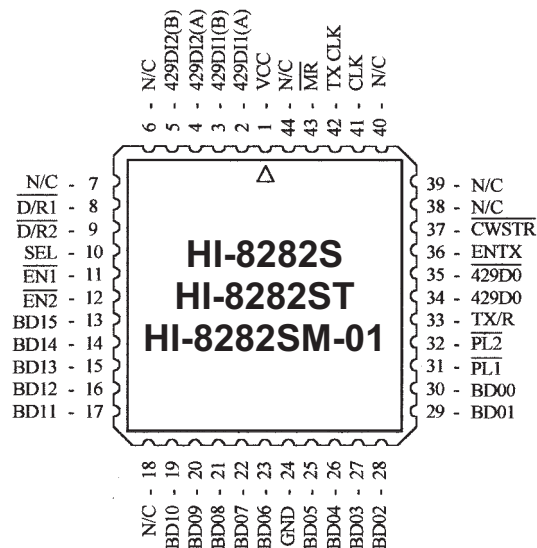
44-PIN PLASTIC PLCC



44-PIN J-LEAD CERQUAD



44-PIN CERAMIC LCC



ORDERING INFORMATION

HI - 8282 x x - xx (Ceramic)

PART NUMBER	TEMPERATURE RANGE	FLOW	BURN IN	NOTES
Blank	-40°C to +85°C	I	No	
T	-55°C to +125°C	T	No	
M-01	-55°C to +125°C	M	Yes	(1)
M-03	-55°C to +125°C	DSCC	Yes	(1) & (2)

PART NUMBER	PACKAGE DESCRIPTION	LEAD FINISH	NOTES
C	40 PIN CERAMIC SIDE BRAZED DIP (40C)	Gold	(3) & (1)
S	44 PIN CERAMIC LEADLESS CHIP CARRIER (44S)	Gold	(3) & (1)
U	44 PIN CERQUAD (44U) not available with 'M' flow	Tin/Lead Solder	

Notes:

- (1) Process Flows M and DSCC always have Tin / Lead (Sn/Pb) solder lead finish.
- (2) DSSC SMD# 5962-8688002QA. Only available in 'C' package with Sn/Pb solder lead finish.
- (3) Gold terminal finish is Pb-Free, RoHS compliant.

HI - 8282J x x - 44 (Plastic)

PART NUMBER	LEAD FINISH
Blank	Tin / Lead (Sn / Pb) Solder
F	100% Matte Tin (Pb-free, RoHS compliant)

PART NUMBER	TEMPERATURE RANGE	FLOW	BURN IN
Blank	-40°C TO +85°C	I	No
T	-55°C TO +125°C	T	No

PART NUMBER	PACKAGE DESCRIPTION
8282J	44 PIN PLASTIC J LEAD (44J) Note (4)

Notes:

- (4) NOT RECOMMENDED FOR NEW DESIGNS. The newer HI-8282APJI and HI-8282APJT replace the HI-8282J-44 and HI-8282JT-44 respectively.

REVISION HISTORY

Revision	Date	Description of Change
DS8282, Rev. G	02/23/09	Clarified the "T" temperature range. Clarified Note (4) in Ordering Information.
Rev. H	07/30/13	Updated Bit Timing section (same as HI-8581) and Receiver Parity information. Update Voltage at ARINC input pins from +/-29V to +/-120V.

inches (millimeters)

Technical drawing of a 16-pin connector showing top, side, and detail views with dimensions in inches and millimeters.

Top View Dimensions:

- Overall Width: $\frac{2.020}{(51.308)} \text{ max}$
- Overall Height: $\frac{.610 \pm .010}{(15.494 \pm .254)}$
- Pin Pitch (Center-to-Center): $\frac{.050}{(1.270)} \text{ typ}$
- Pin Height (from top surface): $\frac{.595 \pm .010}{(15.113 \pm .254)}$

Side View Dimensions:

- Overall Height: $\frac{.600 \pm .010}{(15.240 \pm .254)}$
- Pin Height (from bottom surface): $\frac{.085 \pm .009}{(2.159 \pm .229)}$

Detail View Dimensions:

- Pin Height (from bottom surface): $\frac{.125}{(3.175)} \text{ min}$
- Pin Pitch (Center-to-Center): $\frac{.018}{(.457)} \text{ typ}$
- Pin Pitch (Center-to-Center): $\frac{.100}{(2.54)} \text{ BSC}$
- Pin Height (from bottom surface): $\frac{.010 + .002 / -.001}{(.254 + .051 / -.025)}$

inches (millimeters)

2 1 44 43

$.688 \pm .005$ max
(17.475 ± .127) SQ.

$.620 \pm .012$
(15.748 ± .305)

$.650 \pm .010$
(16.510 ± .254)
SQ.

$.039 \pm .005$
(.990 ± .127)

$.200$
(5.080) max

$.019 \pm .002$
(.483 ± .051)

$.050$
(1.270) BSC

$.100 \pm .007$
(2.540 ± .178)

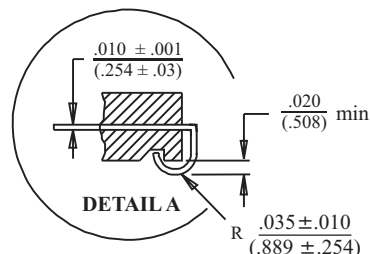
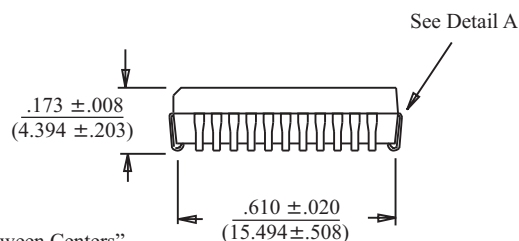
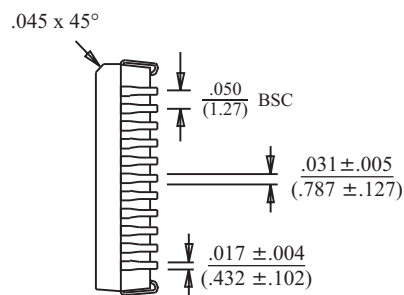
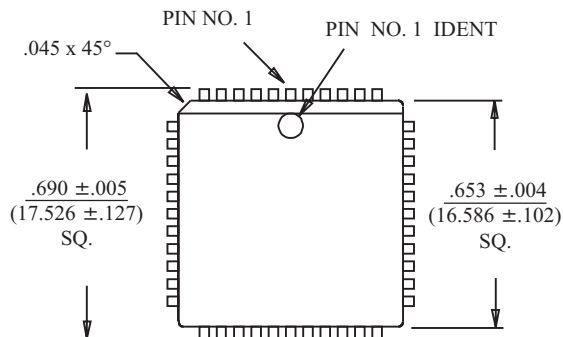
BSC = "Basic Spacing between Centers is theoretical true position dimension"

HOLT INTEGRATED CIRCUITS

44-PIN PLASTIC PLCC

inches (millimeters)

Package Type: 44J

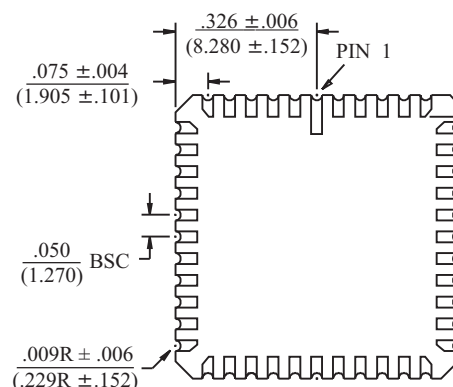
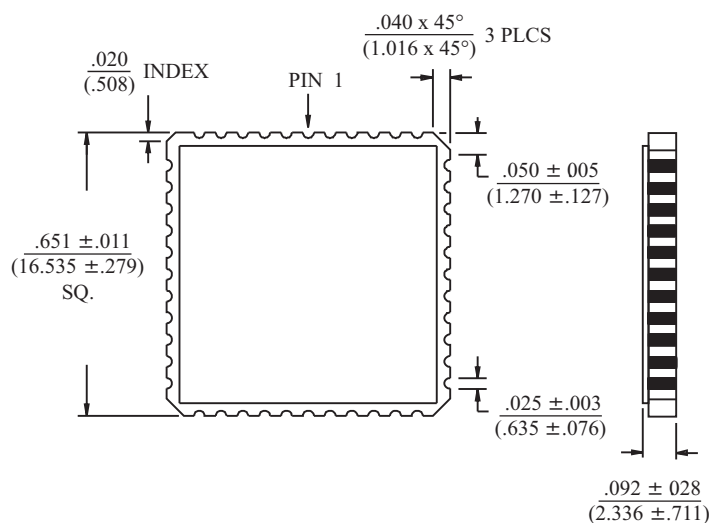


BSC = "Basic Spacing between Centers" is theoretical true position dimension and has no tolerance. (JEDEC Standard 95)

44-PIN CERAMIC LEADLESS CHIP CARRIER

inches (millimeters)

Package Type: 44S



BSC = "Basic Spacing between Centers" is theoretical true position dimension and has no tolerance. (JEDEC Standard 95)